

# IEEE-LAMC 2018

December 12-14, 2018 - Arequipa, Peru.

<http://lamc-ieee.org>

## CALL FOR PAPERS

The Technical Program Committee of the 2018 IEEE MTT-S Latin America Microwave Conference (LAMC) wishes to invite original contributions to this event. The conference includes, but is not limited to, the following topics:

1. Passive components, circuits and devices ( planar and nonplanar components and circuits, filters and multiplexers, tunable devices, and metamaterials).
2. Active devices, circuits and subsystems (RFICs & MMIC design, power amplifiers, linearization techniques, low-noise circuits, signal generation, conversion & control modules, linear and non-linear modeling and characterization).
3. RF systems and applications (microwave systems and front-ends industrial scientific and medical applications, navigation systems, intelligent transportation systems, imaging, sensors, wireless power transmission).
4. Communication systems (terrestrial, vehicular, satellite and indoor applications, wireless and cellular communication systems).
5. Active antennas (phase arrays, integrated antennas, smart antennas, digital-beam forming and MIMO).
6. Signal-power integrity and high-speed digital techniques (EM interference and compatibility, high-speed interconnects, post-silicon validation techniques, power delivery networks, computer simulations and measurements).
7. CAD techniques for RF and microwave engineering (surrogate-based modeling and optimization, space mapping-based methods, model order reduction techniques, statistical analysis and design, EM-based and multiphysics design optimization, EM field theory, time and frequency-domain numerical techniques).

## DEADLINES

**Proposals for special sessions and tutorials: July, 09, 2018**

**Papers submission: August, 06, 2018**

**Notification of acceptance: October, 08, 2018**

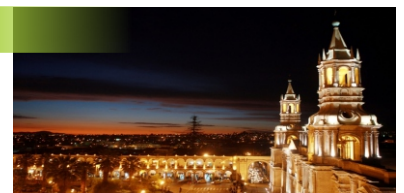
**Accepted papers submission: November, 08, 2018**

Papers submitted to LAMC 2018 will be peer reviewed and evaluated based on originality, quantitative contents, clarity, and interest to the audience. The review process will be single-blind. LAMC will use IEEE EDAS as the electronic paper management system. All accepted and presented papers will be published in the LAMC Conference Proceedings and submitted for inclusion in the IEEE Xplore Digital Library.

English will be the official language of the conference. Prospective authors are cordially invited to submit a three - page two-column manuscript, following the instructions available at the conference website (<http://lamc-ieee.org>).

## EXHIBIT & SPONSORSHIP

The IEEE MTT-S Latin America Microwave Conference also offers an outstanding exhibition and sponsorship opportunity. Please contact our Exhibits Chair.



### General Chair

Guillermo Rafael-Valdivia

Universidad Catolica San Pablo

[grafaelv@ucsp.edu.pe](mailto:grafaelv@ucsp.edu.pe)

### General Co-Chair

Patrick Roblin

Ohio State University

[roblin.1@osu.edu](mailto:roblin.1@osu.edu)

### Technical Program Committee Chair

Efrain Zenteno-Bolaños

Universidad Catolica San Pablo

[ezenteno@ucsp.edu.pe](mailto:ezenteno@ucsp.edu.pe)

### Technical Program Committee Co-Chair

Emmanouil Tentzeris

Georgia Tech, Atlanta

[etentze@ece.gatech.edu](mailto:etentze@ece.gatech.edu)

### Publications Chair

Gonzalo Fernandez Del Carpio

[gfernandezdc@ucsp.edu.pe](mailto:gfernandezdc@ucsp.edu.pe)

### Financial Chair (treasurer)

Efrain Mayhua-Lopez

Universidad Catolica San Pablo

[emayhua@ucsp.edu.pe](mailto:emayhua@ucsp.edu.pe)

### Exhibits Chair

Agustin Vijande

Keysight

[agustinvijande@aqtk.com.pe](mailto:agustinvijande@aqtk.com.pe)



<http://lamc-ieee.org>

